



YETDA INDUSTRY LTD.

Technical Data Sheet

MODEL NO : S2835ANW4-P-BH

3528 Package 3.5(L)*2.8mm(W)*0.8(T)

Chip LEDs

Features :

- Compatible with automatic placement equipment
- Compatible with reflow solder process

Applications :

- Indicators
- Automotive : backlighting in dashboard and switch
- Backlight for LCD

Dice material	Emitted color	Lens Color
InGaN	Blue	Yellow

Electrical/Optical Characteristics(Ta=25°C)

Parameter	Test Condition	Symbol	Value			Unit
			Min	Typ	Max	
CIE Coordinates	IF=150mA	TC	5000	6500	8000	K
Forward voltage	IF=150mA	VF	2.8		3.4	V
Luminous intensity	IF=150mA	Iv	55	65		lm
Viewing angle at 50% Iv	IF=150mA	2θ 1/2		120		Deg
Reverse current	VR=5V	IR			10	μA

Absolute Maximum Ratings(Ta=25°C)

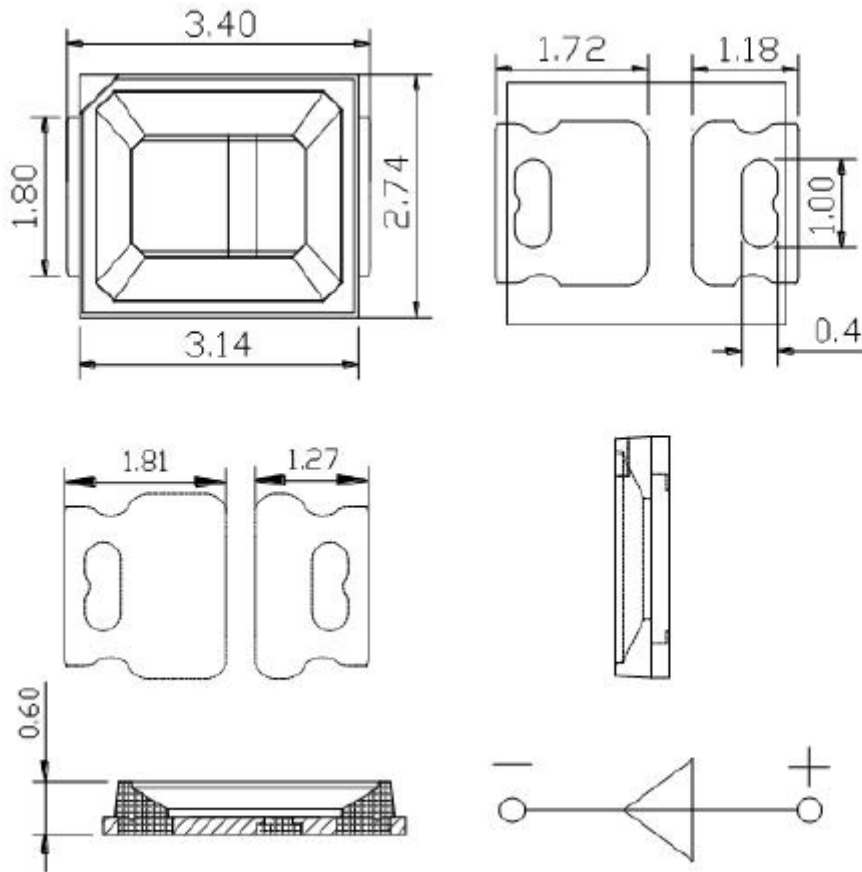
Parameter	Symbol	Value	Unit
Power dissipation	Pd	200	mW
Forward current	IF	60	mA
Reverse voltage	VR	5	V
Operating temperature range	Top	-20 ~+80	°C
Storage temperature range	Tstg	-40 ~+100	°C
Peak pulsing current (1/8 duty f=1kHz)	I _{fp}	200	mA

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PACKAGING DIMENSIONS



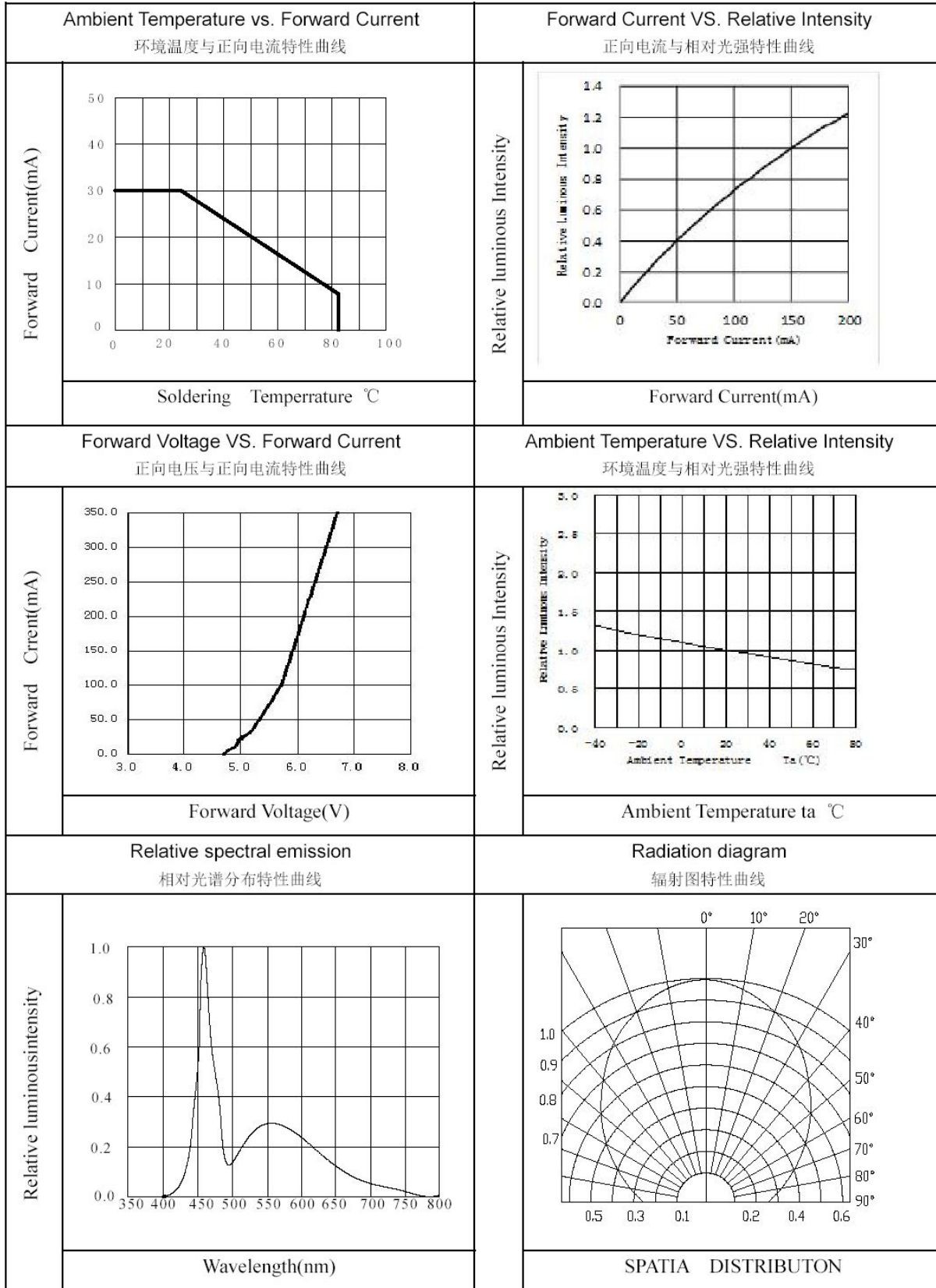
Notes:

1. All dimension units are millimeters.

2. All dimension tolerance is $\pm 0.15\text{mm}$ unless otherwise noted.



Typical Electro-Optical Characteristics Curve:



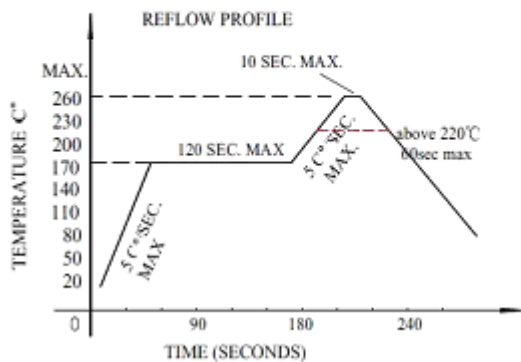


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Precautions For Use :
Over - current - proof
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)
Storage
1. The operation of temperature and R.H. are : $5^{\circ}\text{C} \sim 30^{\circ}\text{C}$, 60%R.H. Max.
2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date) .
3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $60^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 15hrs.

■ Reflow Temp/Time

■ Temperature-profile (Surface of circuit board)
Use the following conditions shown in the figure.



NOTES:

1. We recommend the reflow temperature $245^{\circ}\text{C} (\pm 5^{\circ}\text{C})$. the maximum soldering temperature should be limited to 260°C .
2. dont cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

■ Soldering iron

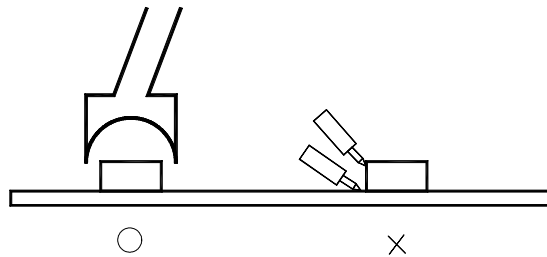
Basic spec is $\leq 5\text{sec}$ when 260°C . If temperature is higher, time should be shorter ($+10^{\circ}\text{C} \rightarrow -1\text{sec}$). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C .



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■ Rework

1. Customer must finish rework within 5 sec under 260°C.
2. The head of iron can not touch copper foil
3. Twin-head type is preferred.



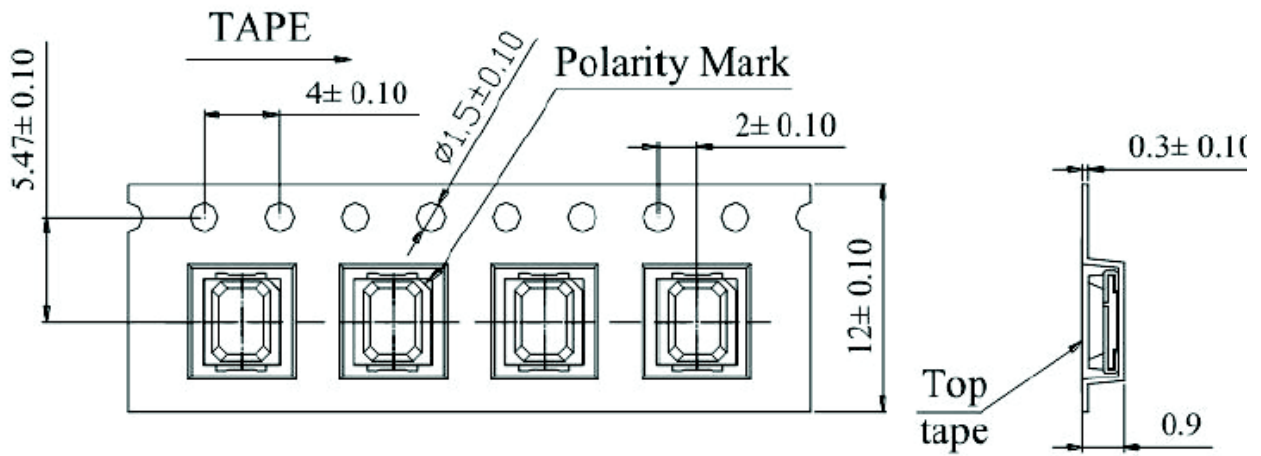
- Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow 、 solder etc.



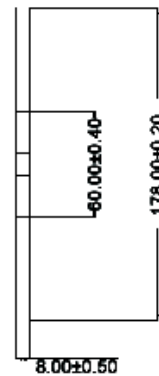
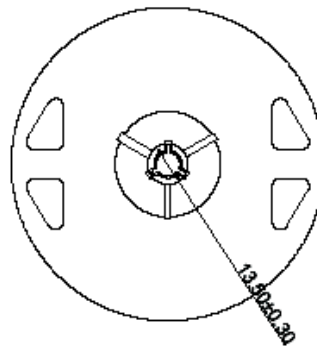
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Tape Specifications (Units : mm)

载带规格 (单位: mm)



Reel Dimensions
卷轴尺寸



■Note

1. Empty component pockets are sealed with top cover tape;
2. The maximum number of missing lamps is two.
3. Package: 4000PCS/REEL